

Title (en)
Multilevel Interconnect Structure

Title (de)
Verbindungsstruktur in mehreren Ebenen

Title (fr)
Structure d'interconnexion à plusieurs niveaux

Publication
EP 0989609 B1 20050209 (EN)

Application
EP 98830562 A 19980925

Priority
EP 98830562 A 19980925

Abstract (en)
[origin: EP0989609A1] The integrated device comprises, in combination: a first conductive region (6); a first insulating region (7) of dielectric material, covering the first conductive region; a first through region (15) of electrically conductive material, extending inside the first insulating region (7), and in direct electrical contact with the first conductive region (6); a second conductive region (10a), arranged above the first insulating region (7), in a position not aligned and not in contact with the first through region (15); a second insulating region (9) of dielectric material, covering the second conductive region (10a); a second through region (21) of electrically conductive material, extending inside the second insulating region (9) as far as the first through region (15), aligned and in direct electrical contact with the first through region; and a third conductive region (11a), arranged above the second insulating region (9), aligned and in direct electrical contact with the second through region (21). <IMAGE>

IPC 1-7
H01L 23/522; **H01L 21/768**

IPC 8 full level
H01L 21/768 (2006.01); **H01L 23/522** (2006.01)

CPC (source: EP US)
H01L 21/768 (2013.01 - EP US); **H01L 23/5226** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US)

Cited by
DE10034020A1; US6908844B2

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DE FR GB IT

DOCDB simple family (publication)
EP 0989609 A1 20000329; **EP 0989609 B1 20050209**; DE 69828968 D1 20050317; US 2002055249 A1 20020509; US 6815328 B2 20041109

DOCDB simple family (application)
EP 98830562 A 19980925; DE 69828968 T 19980925; US 162501 A 20011024